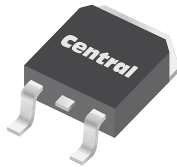
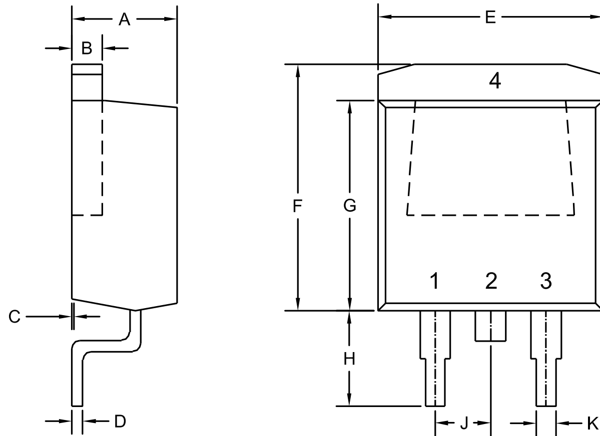
Package Details
D^{2}PAK Case



Mechanical Drawing



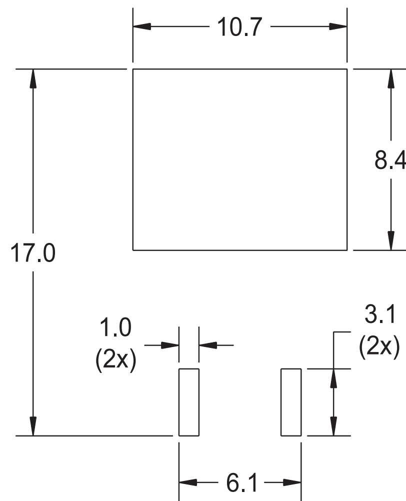
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.163	0.189	4.14	4.80
B	0.045	0.055	1.14	1.40
C	0.000	0.010	0.00	0.25
D	0.012	0.028	0.30	0.70
E	0.386	0.409	9.80	10.40
F	0.378	0.417	9.60	10.60
G	0.335	0.358	8.50	9.10
H	0.197	0.236	5.00	6.00
J	0.093	0.108	2.35	2.75
K	0.030	0.035	0.75	0.90

D2PAK (REV: R2)

Lead Code:
Reference individual
device datasheet.

Part Marking: Full Part Number

Mounting Pad Geometry (Dimensions in mm)

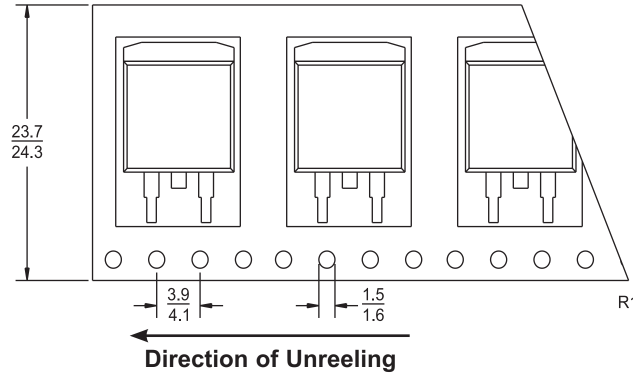


R2 (4-March 2010)

Package Details
D^{2}PAK Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 24mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-2-A

Packaging Base

13” Reel = 800 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code and Ship Date.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13”	3	2,400	15x4x15	38x10x38	12	6
	7	5,600	15x15x9	38x38x23	28	13
	14	11,200	15x15x18	38x38x46	55	25

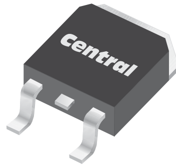
Ordering Information

- For devices taped and reeled on 13” reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R2 (4-March 2010)

Material Composition Specification

D^2PAK Case



Device average mass . . . . 1460 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material (%wt)	Material (mg)	Substance	CAS No.	Substance (%wt)	Substance (mg)	Substance (ppm)
active device	doped Si	0.44%	6.42	Si	7440-21-3	0.44%	6.42	4,397
leadframe	Cu alloy	64.56%	943	Cu	7440-50-8	64.52%	942	645,224
				Fe	7439-89-6	0.03%	0.5	342
die attach	high temperature solder paste	1.13%	16.5	Pb	7439-92-1	1.04%	15.25	10,446
				Sn	7440-31-5	0.06%	0.825	565
				Ag	7440-22-4	0.03%	0.412	282
encapsulation*	EMC	31.98%	467	silica	7631-86-9	21.75%	317.5	217,472
				epoxy resin	29690-82-2	6.4%	93.4	63,974
				phenol resin	9003-35-4	3.2%	46.67	31,967
				Sb_2O_3	1309-64-4	0.32%	4.67	3,199
				Br	7726-95-6	0.32%	4.67	3,199
	EMC GREEN	31.98%	467	silica (fused)	60676-86-0	24.62%	359.5	246,240
				epoxy resin	29690-82-2	3.2%	46.73	32,008
				phenol resin	9003-35-4	3.1%	45.28	31,015
				carbon black	1333-86-4	0.1%	1.4	959
				metal hydroxide	1309-42-8	0.96%	14.0	9,589
plating**	tin/lead process	1.89%	27.6	Sn	7440-31-5	1.7%	24.88	17,042
				Pb	7439-92-1	0.19%	2.76	1,890
	matte tin	1.89%	27.6	Sn	7440-31-5	1.89%	27.64	18,932

*EMC GREEN molding compound is Halogen-Free.
**For Lead Free plating, add suffix “LEAD FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)